



## Multi-Cure® 9-20351-F Flexible Coating/Encapsulant

### APPLICATIONS

- Conformal Coatings

### FEATURES

- UV/Visible Light Cure
- Secondary Heat-Cure Technology
- Corrosion Resistant
- Suitable for Spraying

### OTHER FEATURES

- Isocyanate Free
- One Part, No Mixing Required
- Optimized for Wetting High-Profile Leads

Multi-Cure® 9-20351-F is a flexible, fluorescing, single-component, 100% solids conformal coating specifically formulated for providing a moisture barrier to all electrical devices on the board. This coating has been engineered for application thicknesses between 50 mic [0.002 in] and 0.51 mm [0.020 in]. Ultra Light-Weld® 9-20351-F exhibits excellent adhesion to a variety of metal, ceramic, and glass-filled epoxy surfaces. It is a high-viscosity coating which can be cured by exposure to UV/Visible light and secondarily with heat for shadowed areas on densely populated circuit boards. This product is in full compliance with RoHS directives 2015/863/EU.

UNCURED PROPERTIES *		
Property	Value	Test Method
Solvent Content	No Nonreactive Solvents	N/A
Chemical Class	Acrylated Urethane	N/A
Appearance	Clear Liquid	N/A
Soluble in	Organic Solvents	N/A
Density, g/ml	1.02	ASTM D1875
Viscosity, cP	11,000 (nominal)	ASTM D-2556
Shelf Life at Recommended Conditions from Date of Manufacture	15 months	N/A

OTHER CURED PROPERTIES ‡		
Property	Value	Test Method
Refractive Index (20°C)	1.5	ASTM D542
Boiling Water Absorption, % (2 h)	2.4	ASTM D570
Water Absorption, % (25°C, 24 h)	0.9	ASTM D570
Linear Shrinkage, %	2.4	ASTM D2566
Glass Transition Tg, °C	44	ASTM D5418
CTE $\alpha_1$ , $\mu\text{m}/\text{m}/^\circ\text{C}$	72	ASTM E831
CTE $\alpha_2$ , $\mu\text{m}/\text{m}/^\circ\text{C}$	182	ASTM E831

CURED MECHANICAL PROPERTIES ‡		
Property	Value	Test Method
Durometer Hardness	D60	ASTM D2240
Tensile at Break, MPa [psi]	12.4 [1,800]	ASTM D638
Elongation at Break, %	172	ASTM D638
Modulus of Elasticity, MPa [psi]	110.3 [16,000]	ASTM D638

ADHESION	
Substrate	Recommendation
PCB	✓
ABS (acrylonitrile-butadiene-styrene)	✓
PA6 (polyamide)	✓
PC (polycarbonate)	✓
PVC (polyvinyl chloride)	✓
TPU (thermoplastic polyurethane)	✓

✓ Recommended      ○ Limited Applications  
 † Requires Surface Treatment (e.g. plasma, corona treatment, etc.)

ELECTRICAL PROPERTIES ‡		
Property	Value	Test Method
Volume Resistivity, ohm-cm	500x10E12	ASTM D257
Surface Resistivity, ohm	6,000x10E12	ASTM D257
Dielectric Withstand Voltage, V/mil	500	ASTM D149

\* Not Specifications

N/A Not Applicable

‡ Measured after UV cure followed by 15 days at 25°C/50% RH

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### CURING GUIDELINES

Light-curing guidelines for 9-20351-F at 0.003 in (0.075 mm). Fixture time is defined as the time to develop a shear strength of 0.1 N/mm<sup>2</sup> [10 psi] between glass slides. Actual cure time typically 3-to-5 times fixture time.

Dymax Curing System (Intensity)	Cure Time or Belt Speed
BlueWave® FX-1250 365nm LED (1.7 W/cm <sup>2</sup> ) <sup>A</sup>	20s
UVCS Conveyor with Fusion D lamp (2.5 W/cm <sup>2</sup> ) <sup>B</sup>	1.5 m/min [5 ft/min]

<sup>A</sup> Intensity was measured over the UVA range (350-450 nm) using a Dymax ACCU-CAL™ 50-LED Radiometer.

<sup>B</sup> Intensity was measured over the UVA range (320-395 nm) using a Dymax ACCU-CAL™ 160 Radiometer.

Full cure is best determined empirically by curing at different times and intensities, and measuring the corresponding change in cured properties such as tackiness, adhesion, hardness, etc. Full cure is defined as the point at which more light exposure no longer improves cured properties. Higher intensities or longer cures (up to 5x) generally will not degrade Dymx light-curable materials.

### SECONDARY HEAT CURE

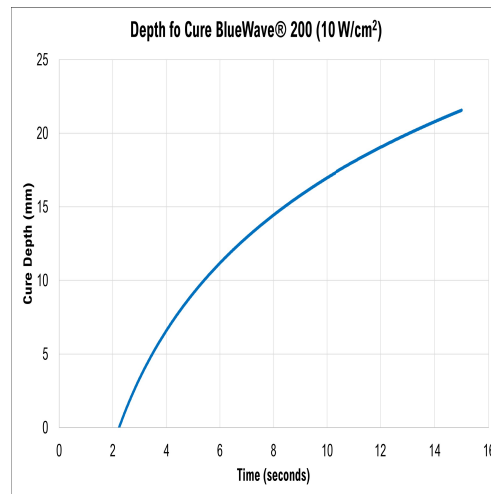
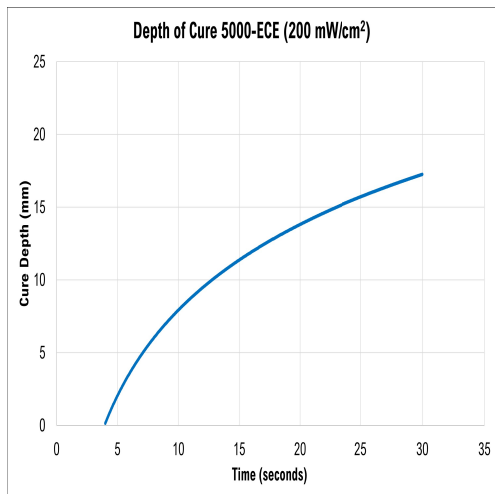
Heat can be used as a secondary cure mechanism where the adhesive cannot be cured with light. Light curing must be done prior to heat cure. The following heat-cure schedule may be used:

Temperature	Time*
110°C [230°F]	60 minutes
120°C [250°F]	30 minutes
150°C [300°F]	15 minutes

\*Note: Actual heat-cure time may vary due to part configuration, volume of adhesive applied, and oven efficiency.

### DEPTH OF CURE

The graph below shows the increase in depth of cure as a function of exposure time. A 9.5 mm [0.37 in] diameter specimen was cured in a polypropylene mold and cooled to room temperature. It was then released from the mold and the cure depth was measured.





## OPTIMIZING PERFORMANCE AND HANDLING

1. This product cures with exposure to UV and visible light as well as moisture. Exposure to ambient and artificial light and moisture should be kept to a minimum before curing. Dispensing components including needles and fluid lines should be 100% light blocking, not just UV blocking.
2. All bond surfaces should be clean and free from grease, mold release, or other contaminants prior to dispensing the adhesive.
3. Cure speed is dependent upon many variables, including lamp intensity, distance from the light source, required depth of cure, bond gap, and percent light transmission of the substrate.
4. Oxygen in the atmosphere may inhibit surface cure. Surfaces exposed to air may require high-intensity UV light to produce a dry surface cure. Flooding the bond area with an inert gas, such as nitrogen, can also reduce the effects of oxygen inhibition.
5. Parts should be allowed to cool after cure before testing and subjecting to any loads.
6. In rare cases, stress cracking may occur in assembled parts. Three options may be explored to eliminate this problem. One option is to heat anneal the parts to remove molded-in stresses. A second option is to open the gap between mating parts to reduce stress caused by an interference fit. The third option is to minimize the amount of time the liquid adhesive remains in contact with the substrate(s) prior to curing.
7. Light curing generally produces some heat. If necessary, cooling fans can be placed in the curing area to reduce the heating effect on components.
8. At the point of curing, an air exhaust system is recommended to dissipate any heat and vapors formed during the curing process.
9. Resealing opened container under a dry, inert gas, such as nitrogen, can help to prolong the shelf life.
10. Light cure is recommended prior to moisture cure. Full cure develops after both light and moisture cure, not one or the other.

## DISPENSING SUPPORT

The Dymax Application Engineering team is ready to discuss your application requirements to provide the most appropriate dispensing and/or spraying solution. Visit our current dispensing equipment portfolio [here](#) or consult our [global contact](#) phone numbers and online chat feature (available in North America only) during normal business hours for instant support.

## STORAGE AND SHELF LIFE

Store the material in a low humidity, cool, and dark place when not in use. This product may polymerize upon prolonged exposure to ambient and artificial light as well as moisture. This material shelf life noted on page 1 of this document, when stored between 10°C (50°F) and 25°C (77°F) in the original, unopened container.

Resealing large containers under dry inert gas, such as nitrogen, can help maintain the shelf life. Smaller syringes and cartridges should be kept in moisture barrier bags with desiccant when not in use.

## CLEAN UP

Uncured Dymax dual-cure materials may be removed from dispensing components and parts with non-alcoholic solvents. Alcoholic solvents (such as IPA or ethanol) that contain moisture activate the curing process. Therefore, it is recommended that non-alcohols such as Butyl Acetate Acetone or MEK be used to cleanup uncured material and purge wetted dispensing lines.

Cured material will be impervious to many solvents and difficult to remove. Cleanup of cured material may require mechanical methods such as ultrasonic bath, water jet, vacuum tweezers, air knife and/or warming to aid in the removal.



## ELECTRONIC CIRCUIT BOARD MATERIALS 9-20351-F Product Data Sheet

### GENERAL INFORMATION

This product is intended for industrial use only. Keep out of the reach of children. Avoid breathing vapors. Avoid contact with skin, eyes, and clothing. Wear impervious gloves. Repeated or continuous skin contact with uncured material may cause irritation. Remove material from skin with soap and water. Never use organic solvents to remove material from skin and eyes. For more information on the safe handling of this material, please refer to the Safety Data Sheet before use.

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### CONTACT DYMAX

[www.dymax.com](http://www.dymax.com)

#### Americas

USA | +1.860.482.1010 | [info@dymax.com](mailto:info@dymax.com)

#### Europe

Germany | +49 611.962.7900 | [info\\_de@dymax.com](mailto:info_de@dymax.com)

Ireland | +353 21.237.3016 | [info\\_ie@dymax.com](mailto:info_ie@dymax.com)

#### Asia

Singapore | +65.67522887 | [info\\_ap@dymax.com](mailto:info_ap@dymax.com)

Shenzhen | +86.755.83485759 | [info@hanarey.com](mailto:info@hanarey.com)

Hong Kong | +852.2460.7038 | [dymaxasia@dymax.com](mailto:dymaxasia@dymax.com)

Korea | +82.31.608.3434 | [info\\_kr@dymax.com](mailto:info_kr@dymax.com)